



Material Content Data Sheet



Sales Product Name	TLE8102SG			Issued	3. July 2019			
MA#	MA005337680							
Package	PG-DSO-12-11			Weight*	406.75 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.431	2.81	2.81	28105	28105
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		170	
	non noble metal	iron	7439-89-6	0.230	0.06		566	
	non noble metal	copper	7440-50-8	230.106	56.56	56.64	565722	566458
	non noble metal	aluminium	7429-90-5	0.346	0.09	0.09	851	851
wire	non noble metal	aluminium	7429-90-5	0.346	0.09	0.09	851	851
encapsulation	organic material	carbon black	1333-86-4	0.300	0.07		739	
	plastics	epoxy resin	-	13.820	3.40		33978	
	inorganic material	silicondioxide	60676-86-0	136.100	33.46	36.93	334606	369323
leadfinish	non noble metal	tin	7440-31-5	4.235	1.04	1.04	10412	10412
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		3	
	non noble metal	nickel	7440-02-0	0.537	0.13	0.13	1320	1323
solder	non noble metal	tin	7440-31-5	0.191	0.05		471	
	noble metal	silver	7440-22-4	0.239	0.06		588	
	non noble metal	lead	7439-92-1	9.139	2.25	2.36	22469	23528
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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